HCM1A0805V2

Automotive grade high current power inductors

Product features

- AEC-Q200 qualified
- High current carrying capacity
- Magnetically shielded, low EMI
- DC-DC converter applications up to 1 MHz
- Filtering applications up to Self Resonant Frequency (SRF) [See product specification table]
- Inductance range from 0.22 µH to 47 µH
- Current range from 2.5 A to 50 A
- 8.4 mm x 8.0 mm footprint surface mount package in a 5.4 mm height
- Moisture Sensitivity Level (MSL): 1
- Alloy powder core material

Applications

- Body electronics
  - Central body control module
  - Vehicle access control system
  - Headlamps, tail lamps and interior lighting and LED lighting
  - Heating ventilation and air conditioning controllers (HVAC)
  - Doors, window lift and seat control
- Advanced driver assistance systems
  - Adaptive cruise control (ACC)
  - Automatic parking control
  - Collision avoidance system/ Car black box system
- Infotainment and cluster electronics
  - Audio subsystem: head unit and trunk amp
  - Digital instrument cluster
  - In-vehicle infotainment (IVI) and navigation
  - Port power/USB HUB for front and rear passengers
- Chassis and safety electronics
  - Airbag control unit
  - Electronic stability control system (ESC)
- Engine and Powertrain Systems
  - Electric pumps, motor control and auxiliaries
  - Powertrain control module (PCU)/ Engine Control unit (ECU)
  - Transmission Control Unit (TCU)

Environmental compliance and general specifications

- Storage temperature range (Component): -55 °C to +155 °C
- Operating temperature range: -55 °C to +155 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 (latest revision) compliant

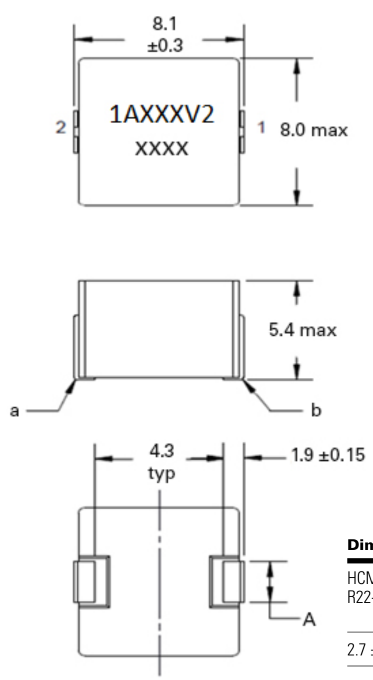
Powering Business Worldwide

Product specifications

Part number[6]	OCL[1] (µH) ± 20%	FLL[2] (µH) minimum	I_{rms}[3] (A)	I_{sat}[4] (A)	DCR (mΩ) typical @ +20 °C	DCR (mΩ) maximum @ +20 °C	SRF (MHz) typical	K-factor[5]
HCM1A0805V2-R22-R	0.22	0.14	28	50	0.92	1.2	170	452
HCM1A0805V2-R47-R	0.47	0.30	19	26	2.1	2.8	80	300
HCM1A0805V2-R68-R	0.68	0.43	17	22	2.73	3.5	70	288
HCM1A0805V2-1R0-R	1.0	0.64	14	15	4.0	4.8	40	265
HCM1A0805V2-2R2-R	2.2	1.41	10.5	9.6	7.0	8.5	23	174
HCM1A0805V2-3R3-R	3.3	2.1	9.2	7.2	9.0	10	19	165
HCM1A0805V2-4R7-R	4.7	3.0	8.0	8.0	13	15.6	15	122
HCM1A0805V2-100-R	10	6.4	4.0	6.2	49	60	12	61
HCM1A0805V2-150-R	15	9.6	4.0	4.6	43	52	8.0	63
HCM1A0805V2-220-R	22	14	3.5	4.0	60.7	70	6.5	53
HCM1A0805V2-330-R	33	21	2.7	4.0	103	125	5.5	48
HCM1A0805V2-470-R	47	30	2.5	2.6	125	137	4.5	37

1. Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.25 V_{rms}, 0.0 Adc, +25 °C
2. Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.25 V_{rms}, I_{sat}, , +25 °C
3. I_{rms}: DC current for an approximate temperature rise of 30 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +155 °C under worst case operating conditions verified in the end application.
4. I_{sat}: Peak current for approximately 20% rolloff @ +25 °C
5. K-factor: Used to determine B_{p-p} for core loss (see graph). Bp-p = K * L * ΔI. B_{p-p}: (Gauss), K: (K-factor from table), L: (Inductance in µH), ΔI (Peak to peak ripple current in Amps).
6. Part Number Definition: HCM1A0805V2-xxx-R
   HCM1A0805V2 = Product code and size
   xxx= inductance value in µH, R= decimal point,
   If no R is present then last character equals number of zeros
   -R suffix = RoHS compliant

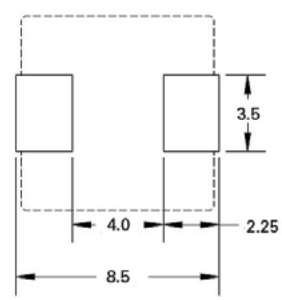
Dimensions (mm)



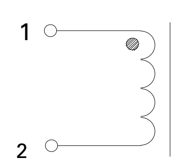
Dimension A

HCM1A0805V2-R22-R,	HCM1A0805V2-R47, R68-R	HCM1A0805V2-1R0 through 470-R
2.7 ±0.2	1.8 ±0.3	3.0 ±0.2

Recommended pad layout



Schematic

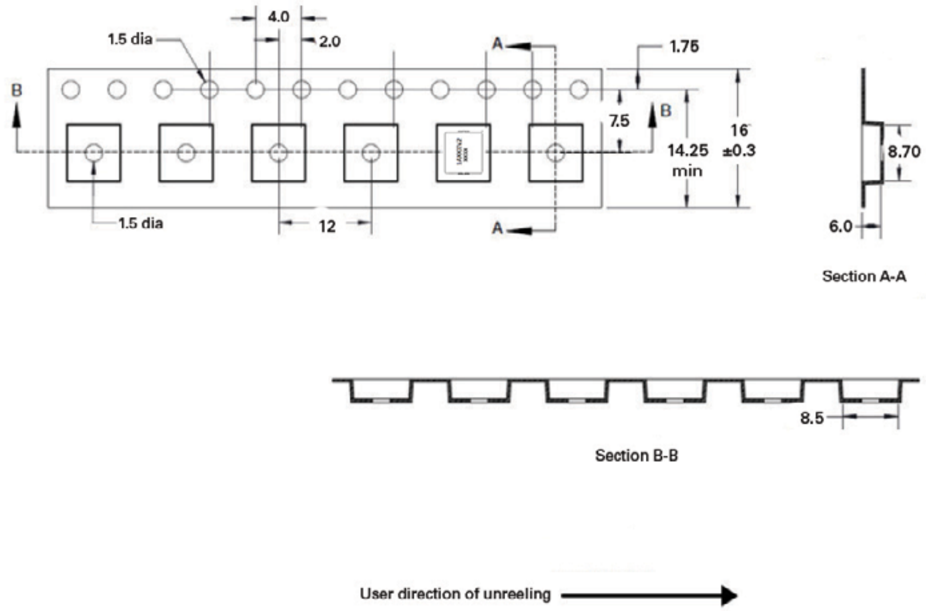


Part marking: 1AxxxV2, xxx=inductance value in uH, R=decimal point. If no R is present then last character equals number of zeros. xxxx=Lot code
All soldering surfaces to be coplanar within 0.1 millimeters
Tolerances are ±0.3 millimeters unless stated otherwise
Pad layout tolerances are ±0.1 millimeters unless stated otherwise
DCR measured from point “a” to point “b”
Traces or vias underneath the inductor is not recommended

Packaging information (mm)

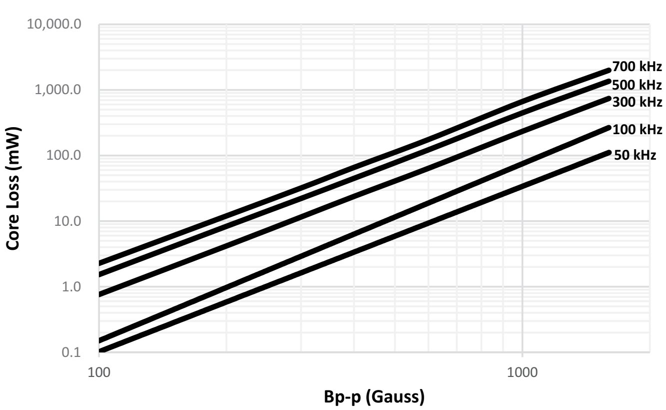
Drawing not to scale

Supplied in tape and reel packaging, 500 parts per 13” diameter reel

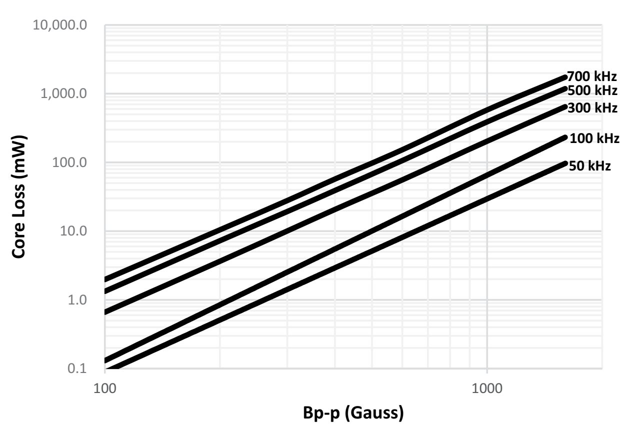


Core loss vs $B_{p\text{-}p}$

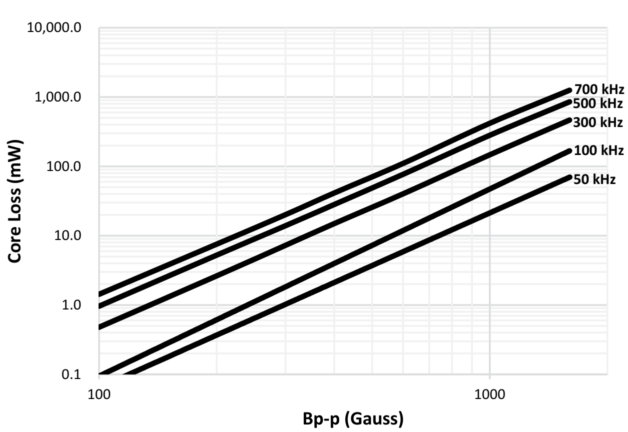
HCM1A0805V2-R22-R



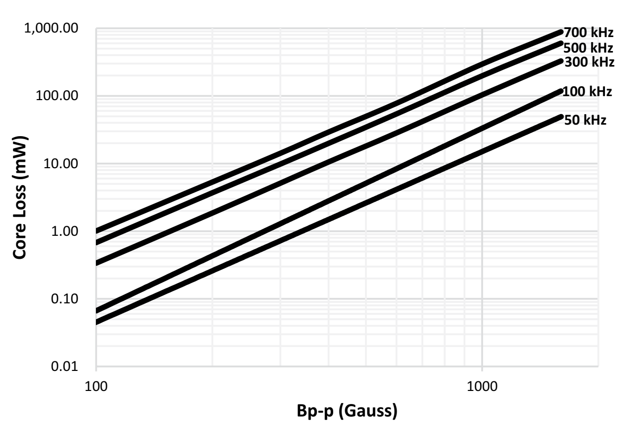
HCM1A0805V2-R47-R



HCM1A0805V2-R68-R

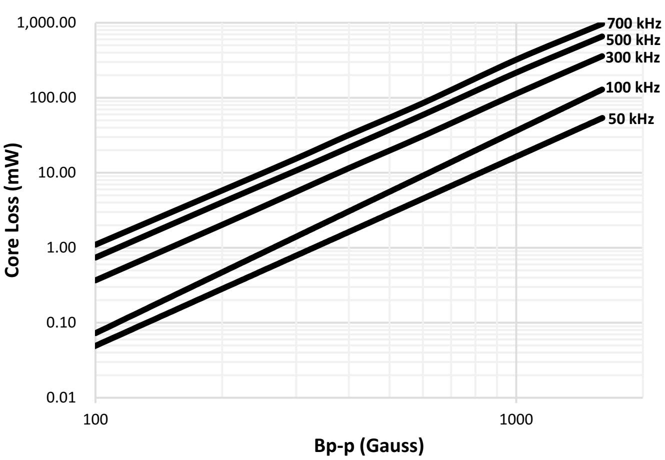


HCM1A0805V2-1R0-R

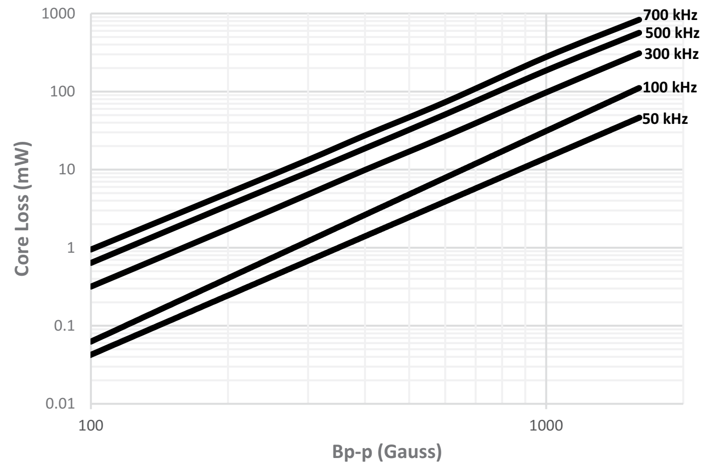


Core loss vs $B_{p\text{-}p}$

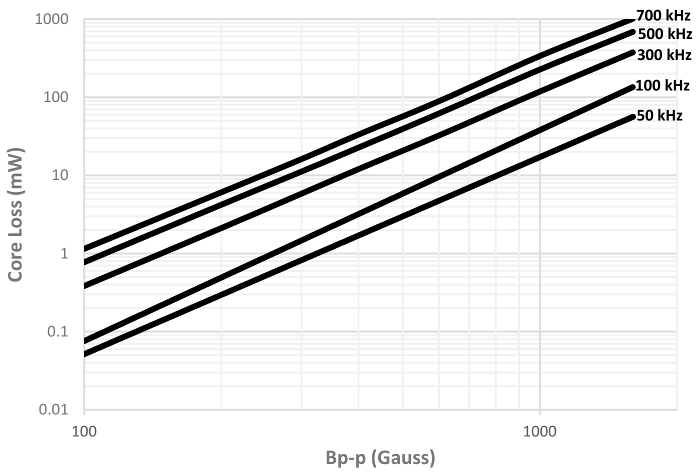
HCM1A0805V2-2R2-R



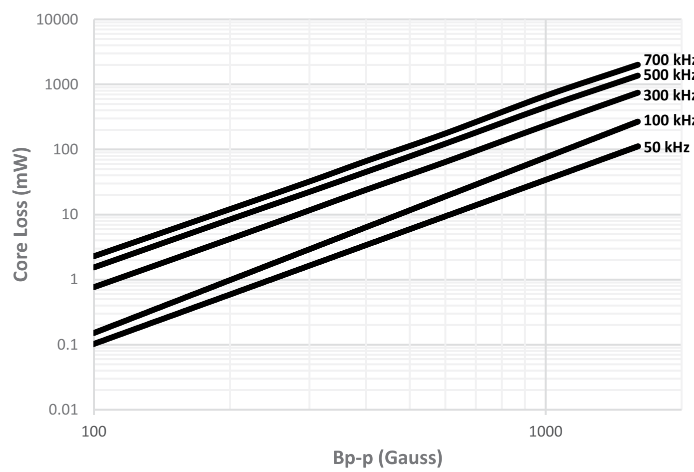
HCM1A0805V2-3R3-R



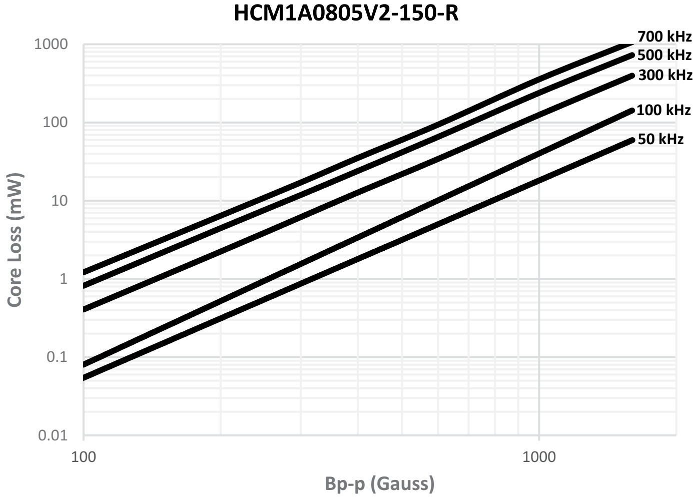
HCM1A0805V2-4R7-R



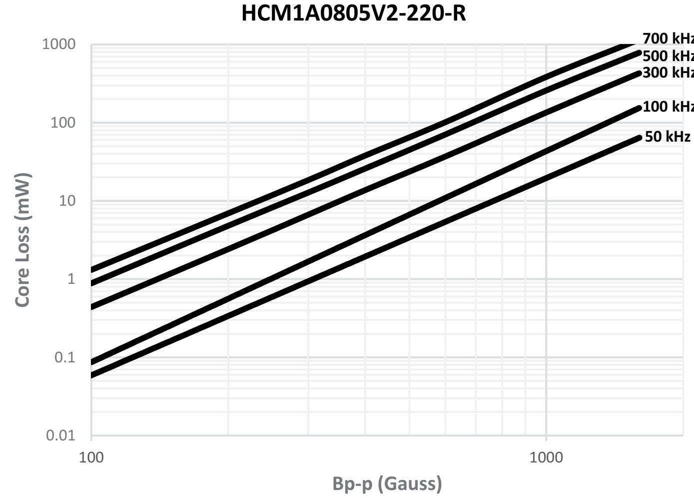
HCM1A0805V2-100-R



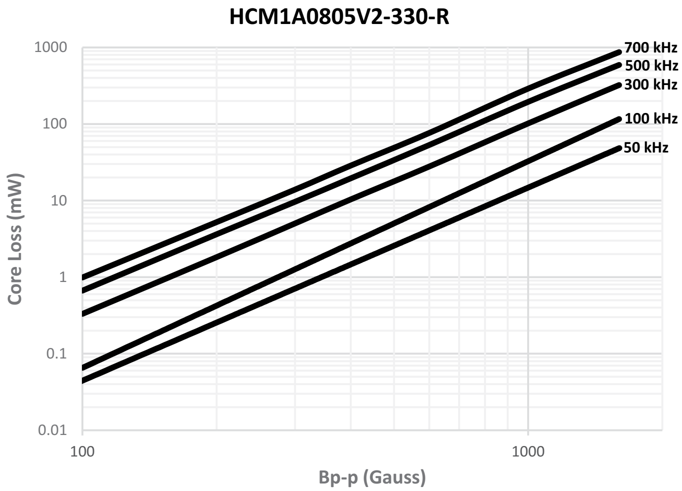
HCM1A0805V2-150-R

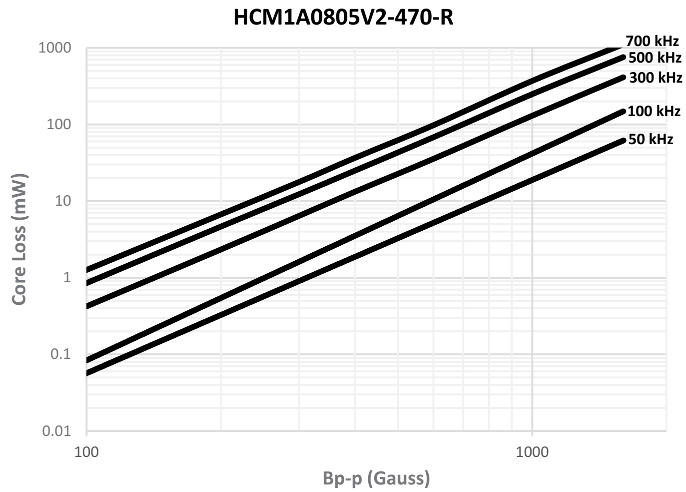


HCM1A0805V2-220-R

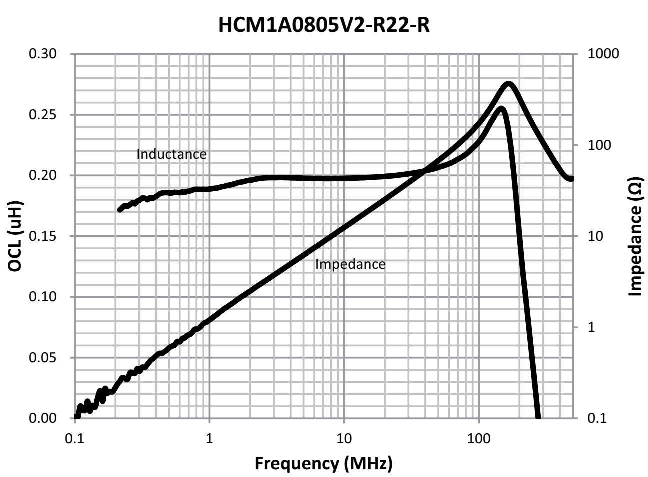


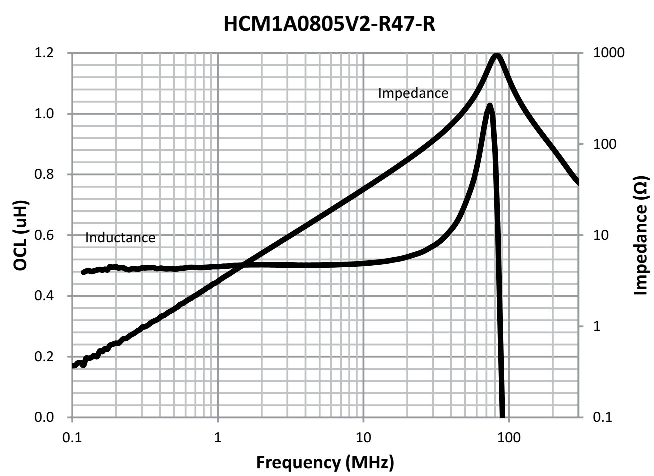
Core loss vs B_{p-p}

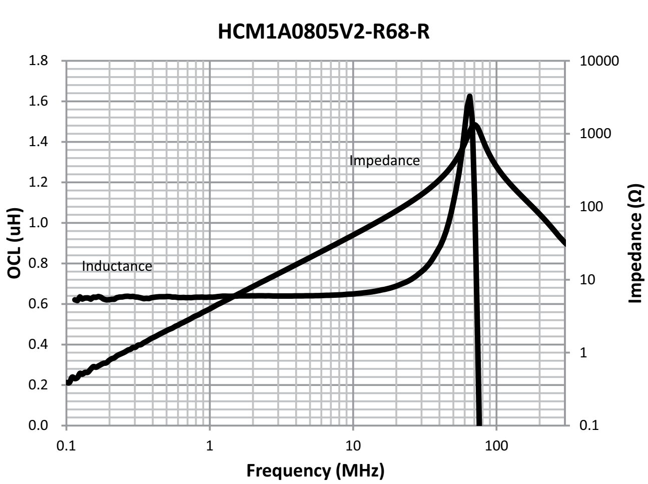


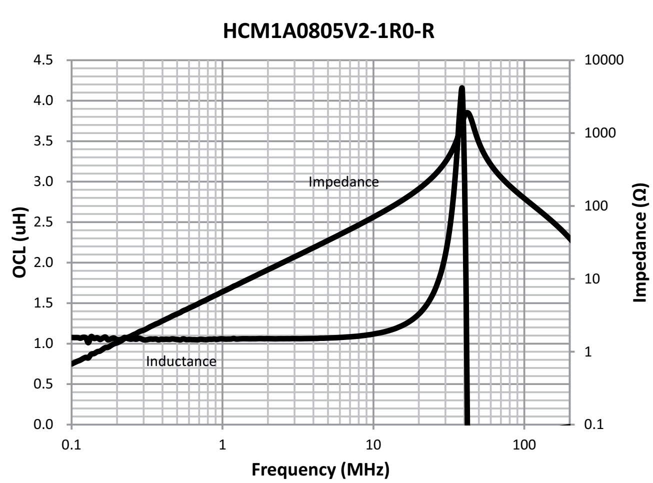


Inductance and impedance vs. frequency

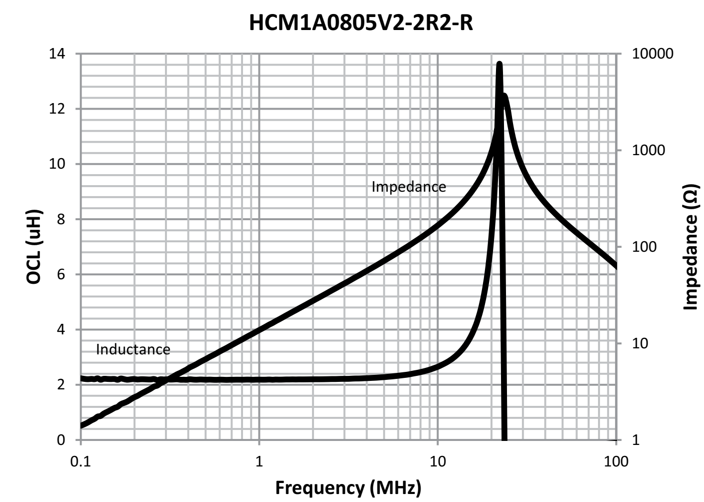


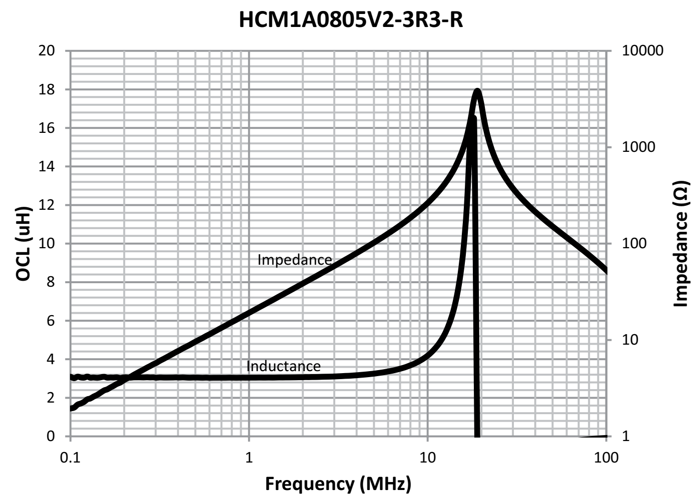


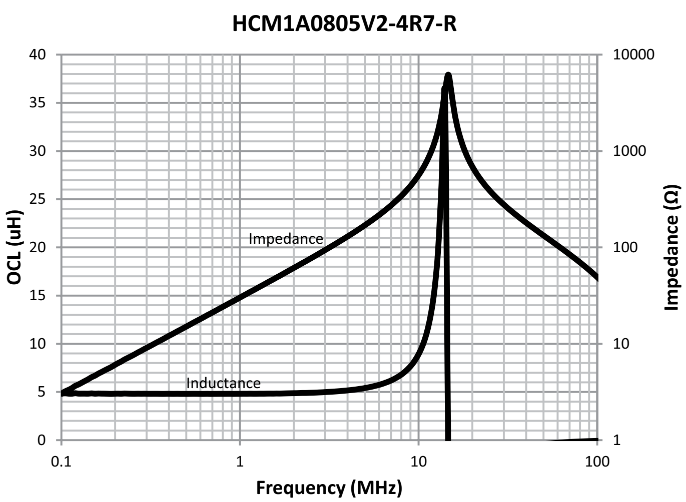


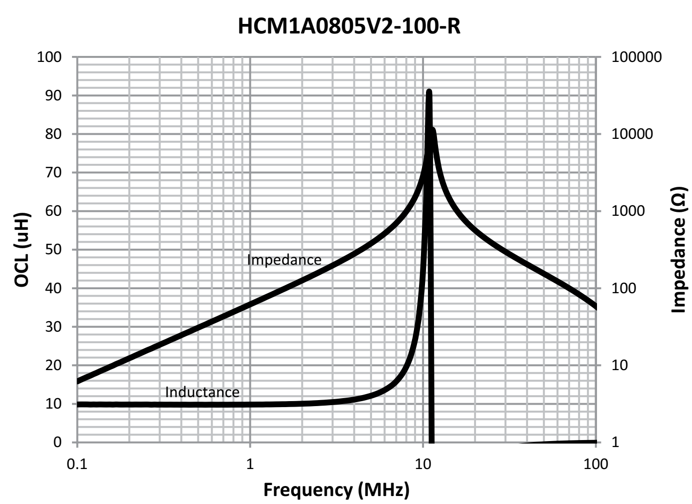


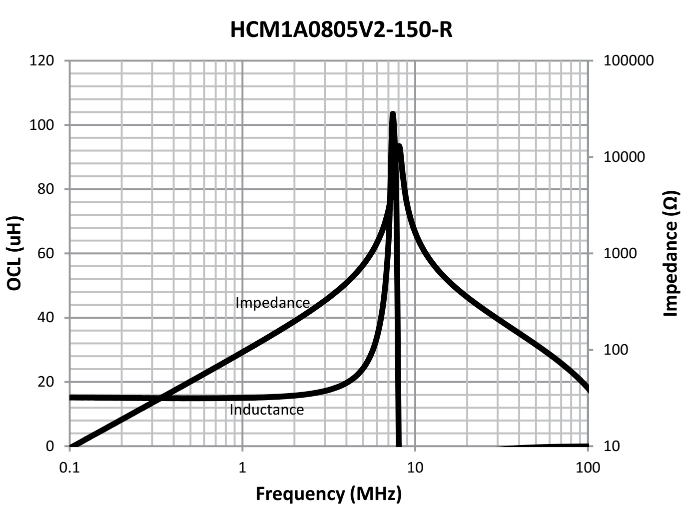
Inductance and impedance vs. frequency

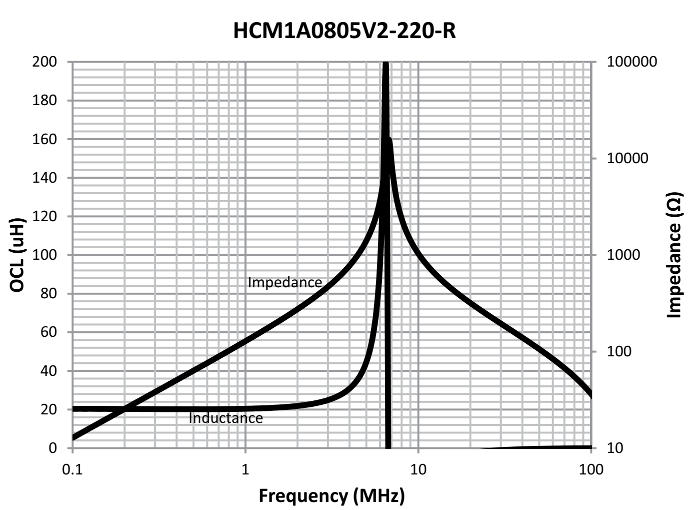




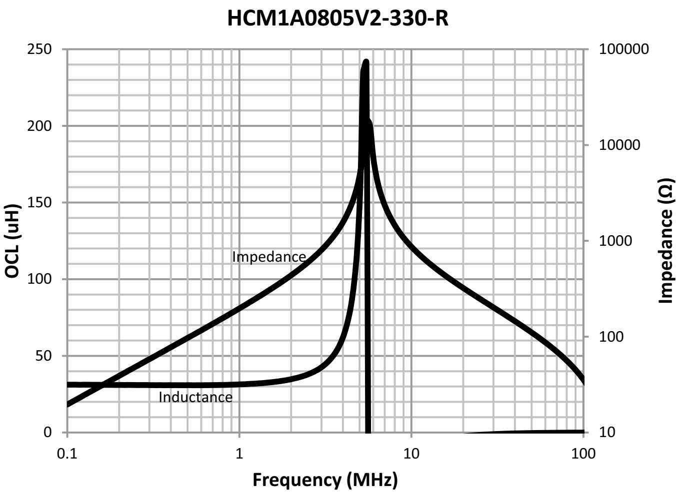


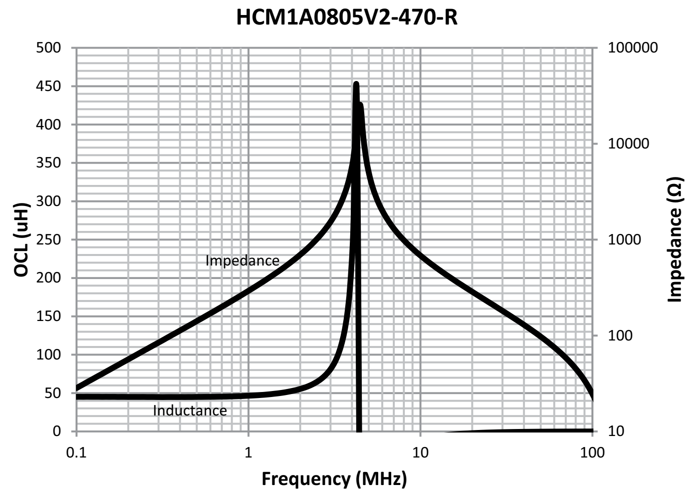




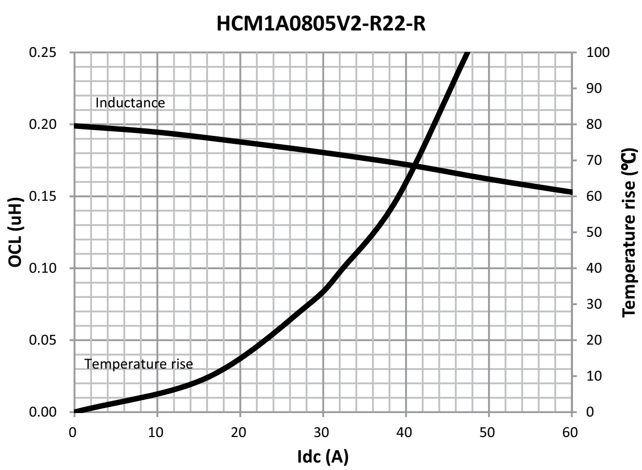


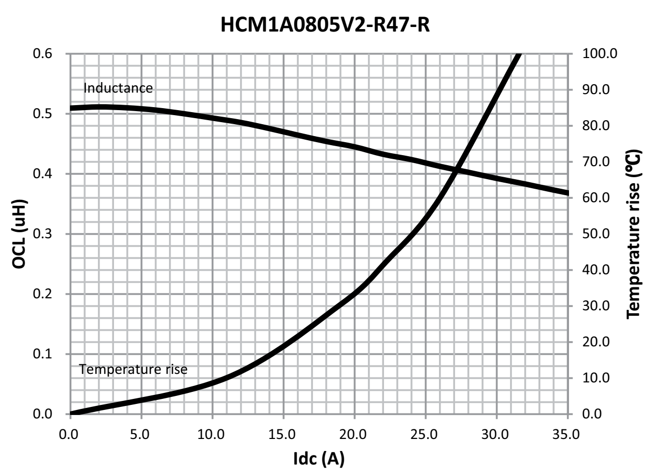
Inductance and impedance vs. frequency

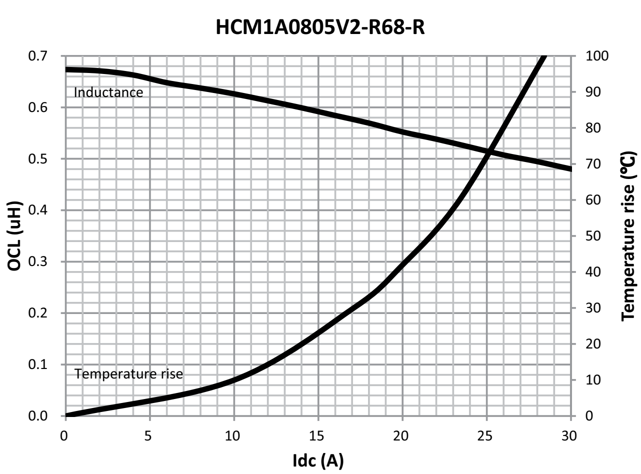


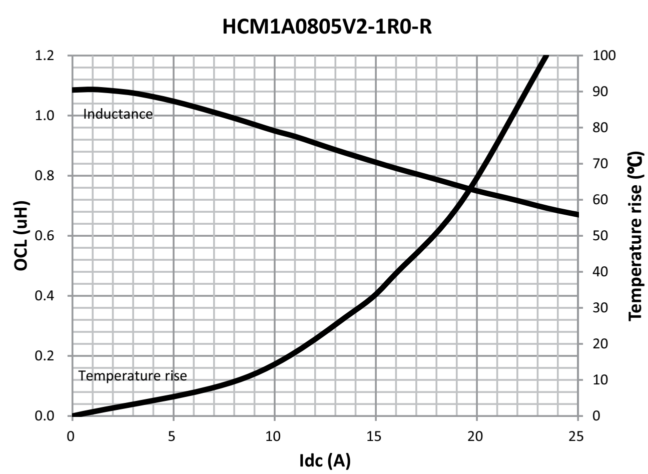


Inductance and temperature rise vs. current

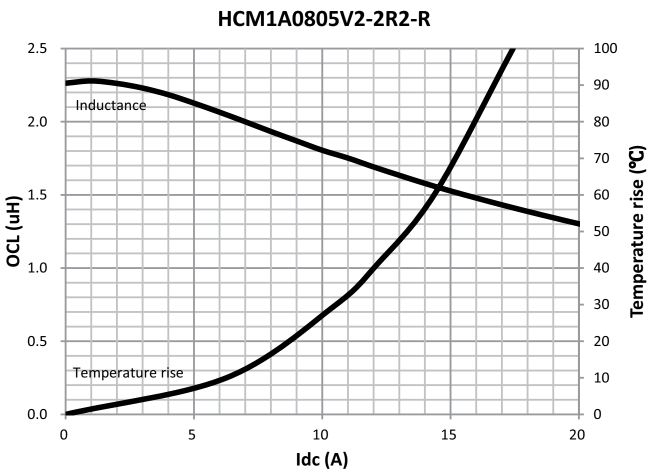


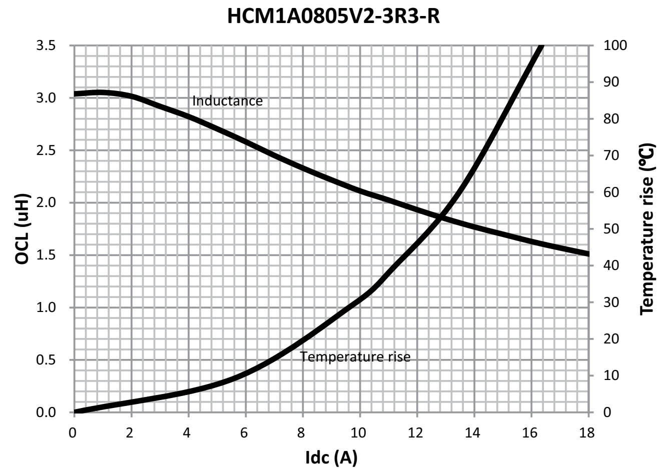


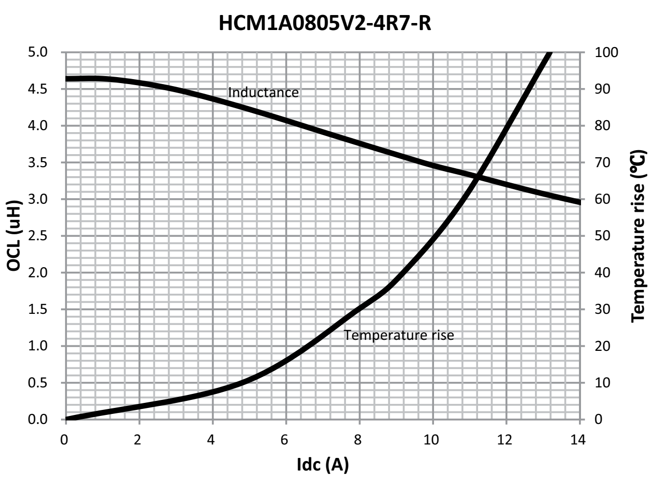


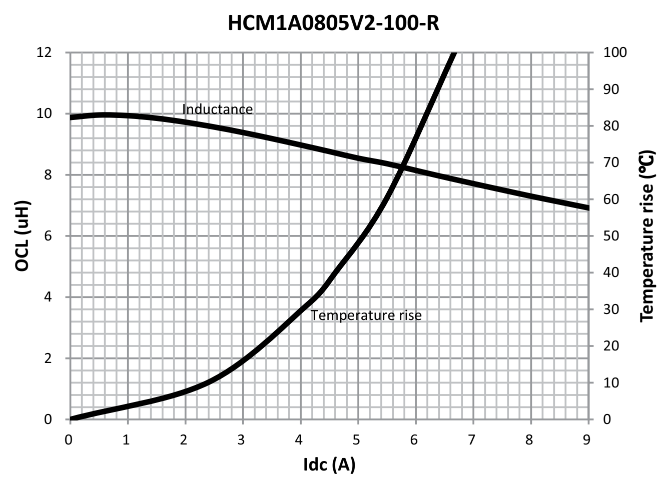


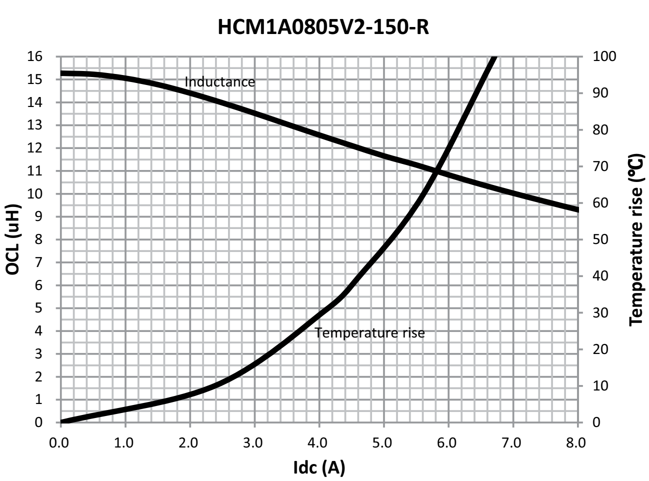
Inductance and temperature rise vs. current

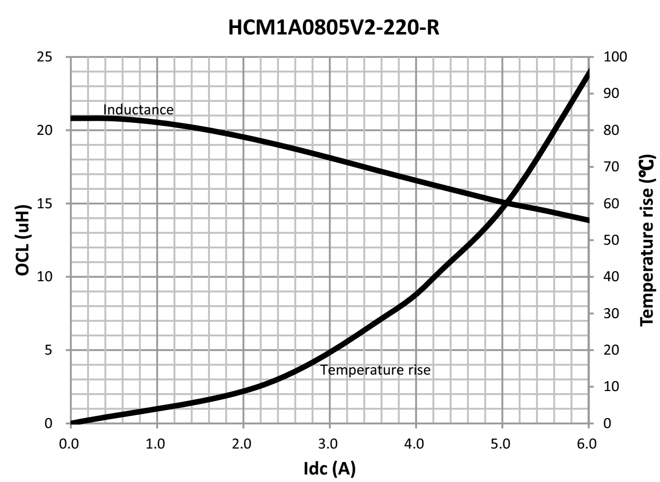




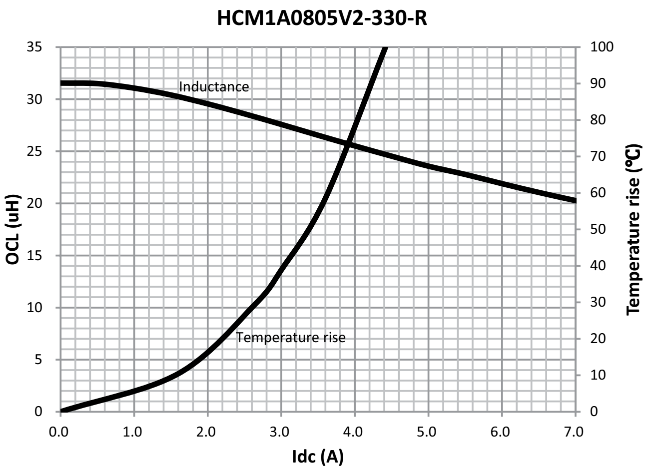


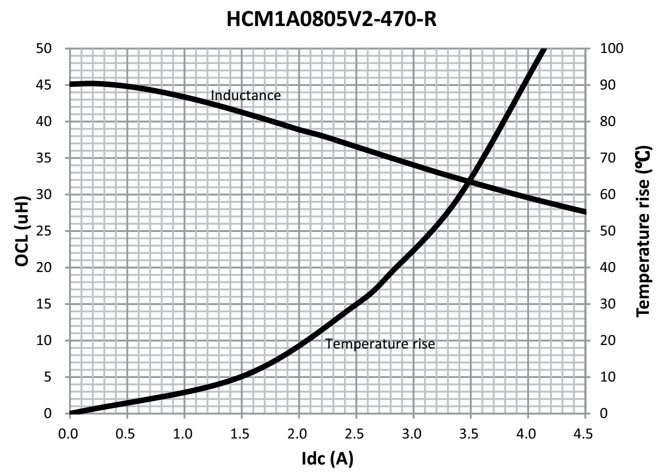






Inductance and temperature rise vs. current





Solder reflow profile

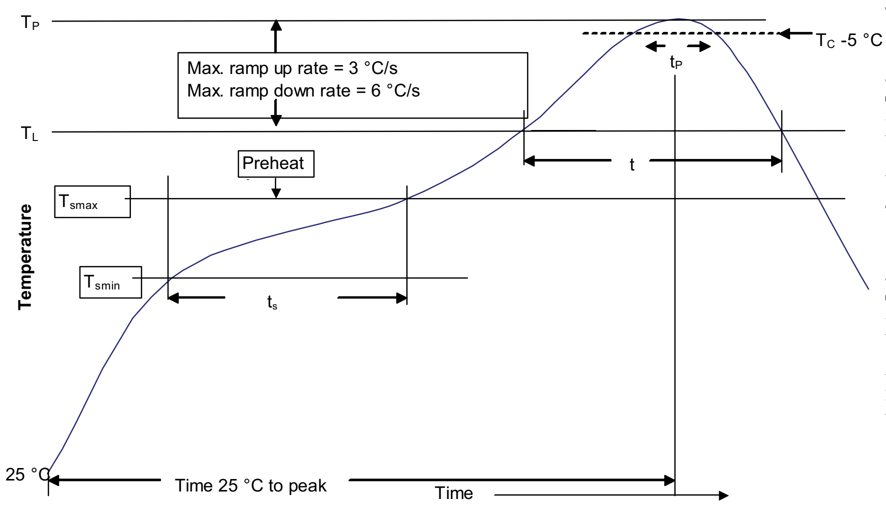


Table 1 - Standard SnPb solder (T_c)

Package thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) free solder (T_c)

Package thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Reference J-STD-020

Profile feature		Standard SnPb solder	Lead (Pb) free solder
Preheat and soak	• Temperature min. (T_{smin})	100 °C	150 °C
	• Temperature max. (T_{smax})	150 °C	200 °C
	• Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Ramp up rate T_L to T_p		3 °C/ second max.	3 °C/ second max.
Liquidous temperature (T_L) Time (t_L) maintained above T_L		183 °C 60-150 seconds	217 °C 60-150 seconds
Peak package body temperature (Tp)*		Table 1	Table 2
Time (t_p)* within 5 °C of the specified classification temperature (T_c)		20 seconds*	30 seconds*
Ramp-down rate (T_p to T_L)		6 °C/ second max.	6 °C/ second max.
Time 25 °C to peak temperature		6 minutes max.	8 minutes max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

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Publication No. 10902 BU-MC18060
April 2020